

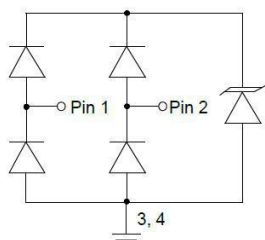
Features

- 75W Peak Pulse Power Per Line(8/20us)
- 5V Working Peak Reverse Voltage
- Peak Pulse Current:5A
- ESD per IEC 61000-4-2(Contact):15KV
- ESD per IEC 61000-4-2(Air):25KV
- Clamping Voltage @IPP=1A:10V
- Junction Capacitance:0.6PF
- Package:DFN1610-6 (1.6x1.0x0.75mm)
- Polarity: Unidirectional

Mechanical Characteristics

- Mechanical Characteristics
- Lead Finish: NiPdAu
- Case Material: “ Green ” Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminal Connections: See Diagram Below
- Marking Information: See Below

Schematic And Configuration



Circuit Schematic

Ordering Information

Part Number	Packaging	Reel Size
TEVR0R6V05D2X	Tape & Reel	7inch

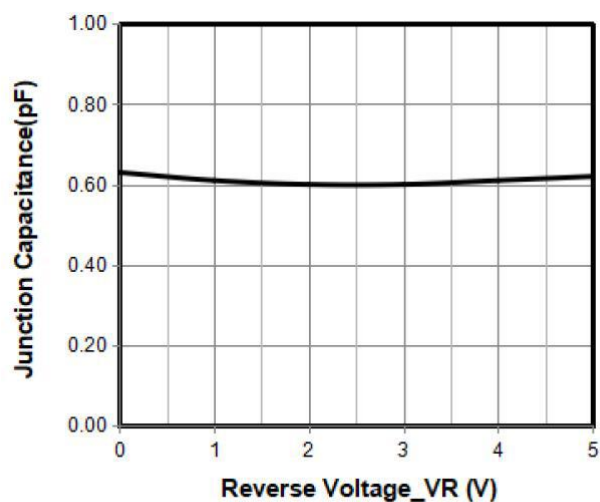
Absolute Maximum Ratings (Ta=25°C,RH=45%-75%,unless otherwise noted)

Parameter	Symbol	Value	Unit
Operating Temperature Range	Tj	-55~+125	°C
Storage Temperature Range	Tstg	-55~+150	°C

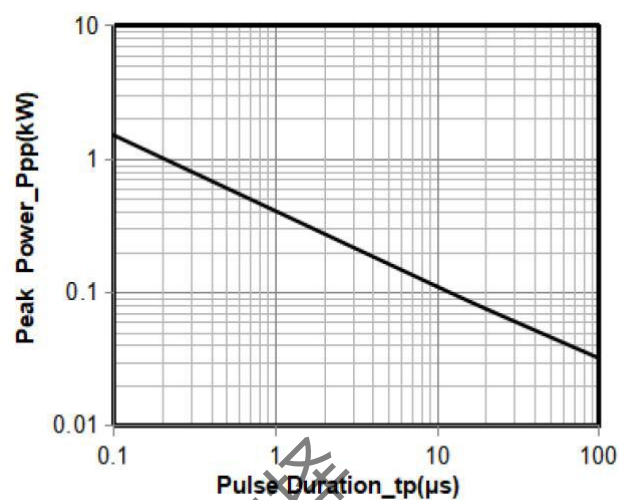
Electrical Characteristics (Ta=25°C)

Parameter	Symbol	Min	Type	Max	Unit	Test Condition
Reverse Working Voltage	Vrwm			5	V	
Breakdown Voltage	Vbr	6			V	It=1mA
Reverse Leakage Current	Ir			0.5	uA	Vrwm=5V
Clamping Voltage	Vc		8.3	10	V	Ipp=1A(8×20us pulse)
Juntion Capacitance	Cj		0.3	0.4	pF	Vr=0V,f=1MHz,I/O to I/O
			0.6	0.8	pF	Vr=0V,f=1MHz,I/O to GND

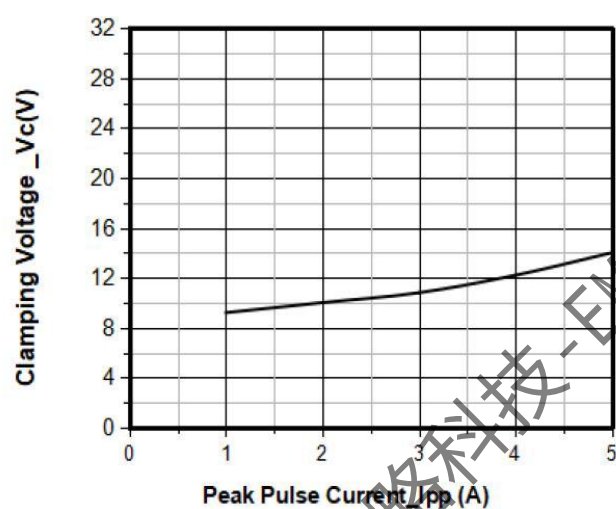
Typical Performance Characteristics (Ta=25°C, unless otherwise noted)



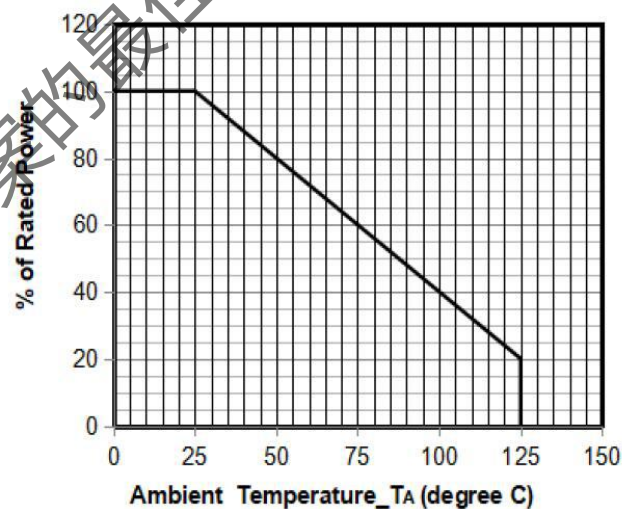
Junction Capacitance vs. Reverse Voltage



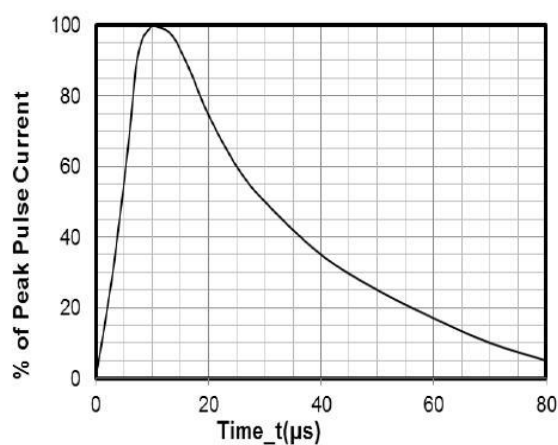
Peak Pulse Power vs. Pulse Time



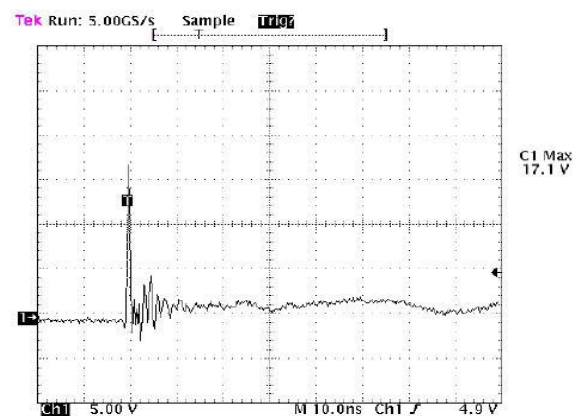
Clamping Voltage vs. Peak Pulse Current



Power Derating Curve



8 X 20μs Pulse Waveform



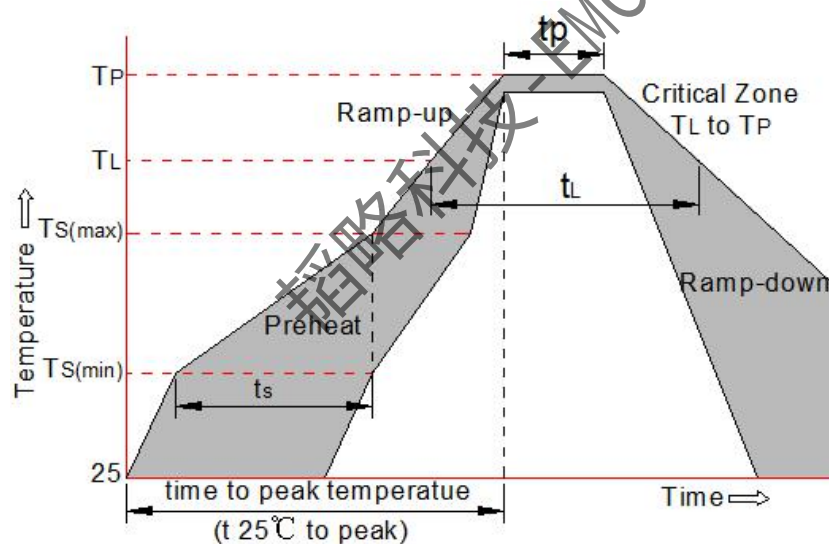
Note: Data is taken with a 10x attenuator

ESD Clamping Voltage

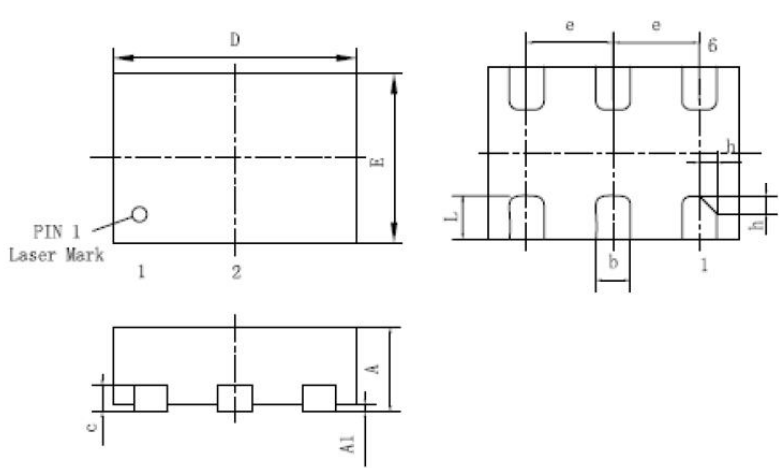
+8 kV Contact per IEC61000-4-2

Soldering Parameters

Reflow Condition		Pb-Free Assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L) (Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_p)		8 min. Max
Do not exceed		+260°C

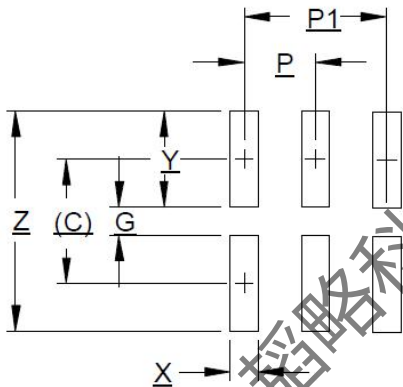


Package Mechanical Data



SYM	DIMENSIONS		
	MILLIMETERS		
	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	--	0.02	0.05
b	0.17	0.20	0.25
c	0.15	0.20	0.25
D	1.55	1.60	1.65
E	0.90	1.00	1.10
e	0.50 BSC		
L	0.20	0.25	0.30
h	0.08	0.10	0.12

Suggested Land Pattern



SYM	DIMENSIONS	
	MILLIMETERS	INCHES
C	0.87	0.034
G	0.19	0.07
P	0.50	0.020
P1	1.00	0.039
X	0.20	0.008
Y	0.68	0.027
Z	1.55	0.061

Contact Information

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